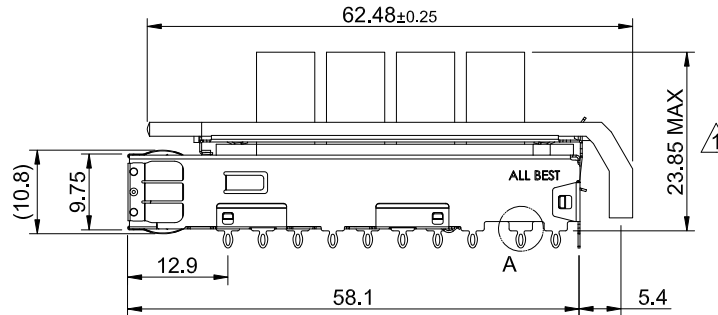
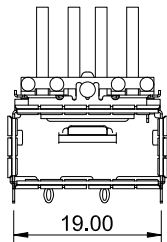
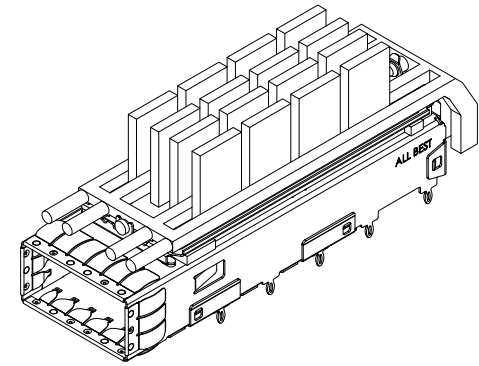


DETAIL A
SCALE 5:1



MATERIAL
 CAGE: NICKEL SILVER
 HEAT SINK: ALUMINUM
 HEAT SINK CLIP: STAINLESS STEEL
 EMI SPRING: STAINLESS STEEL
 LIGHT PIPE: PC

FINISH
 HEAT SINK: ANODE PROCESS

NOTE
 ⚠️ DIMENSION APPLIES WITH MODULE INSERTED IN CAGE



TITLE: QSFP+ 1X1 Cage Assembly w/ Light Pipe & Heat Sink

DWG#: R-OR-Q1-4CMEE

SHEET: 1/4
 REV. B

UNIT: mm
 SCALE: A4 1:1

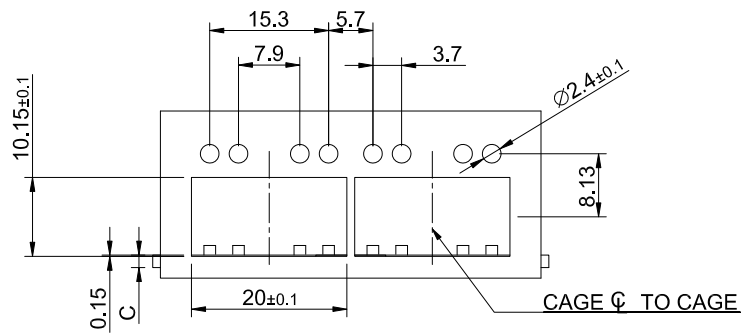
FINISH: CHECKED: Gary Kang

THIRD ANGLE PROJECTION

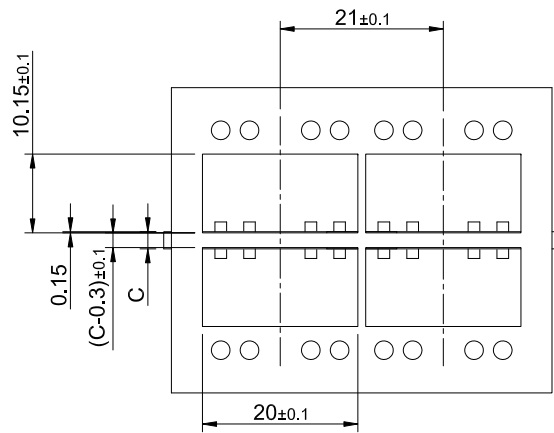
MATERIAL: RoHS Compliant
 APPROVED: George Yang

TOLERANCE: Angle: ± 1°
 X: ± 0.25 .X: ± 0.20 .XX: ± 0.15

DRAWN: Boris
 DATE: 09/06/2016

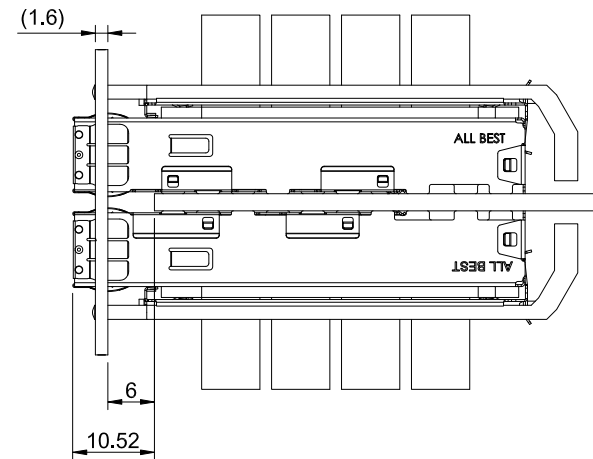
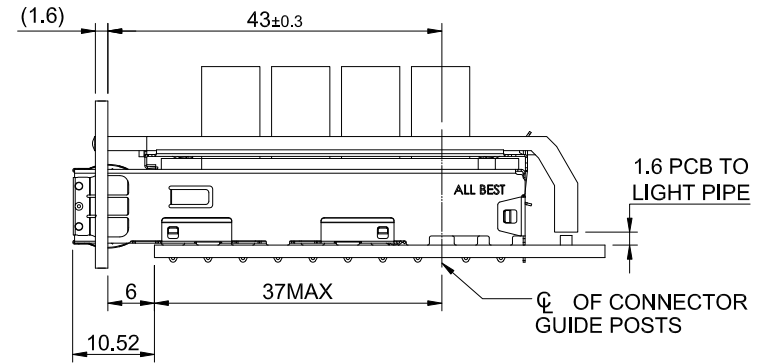



ONE SIDED CONFIGURATION

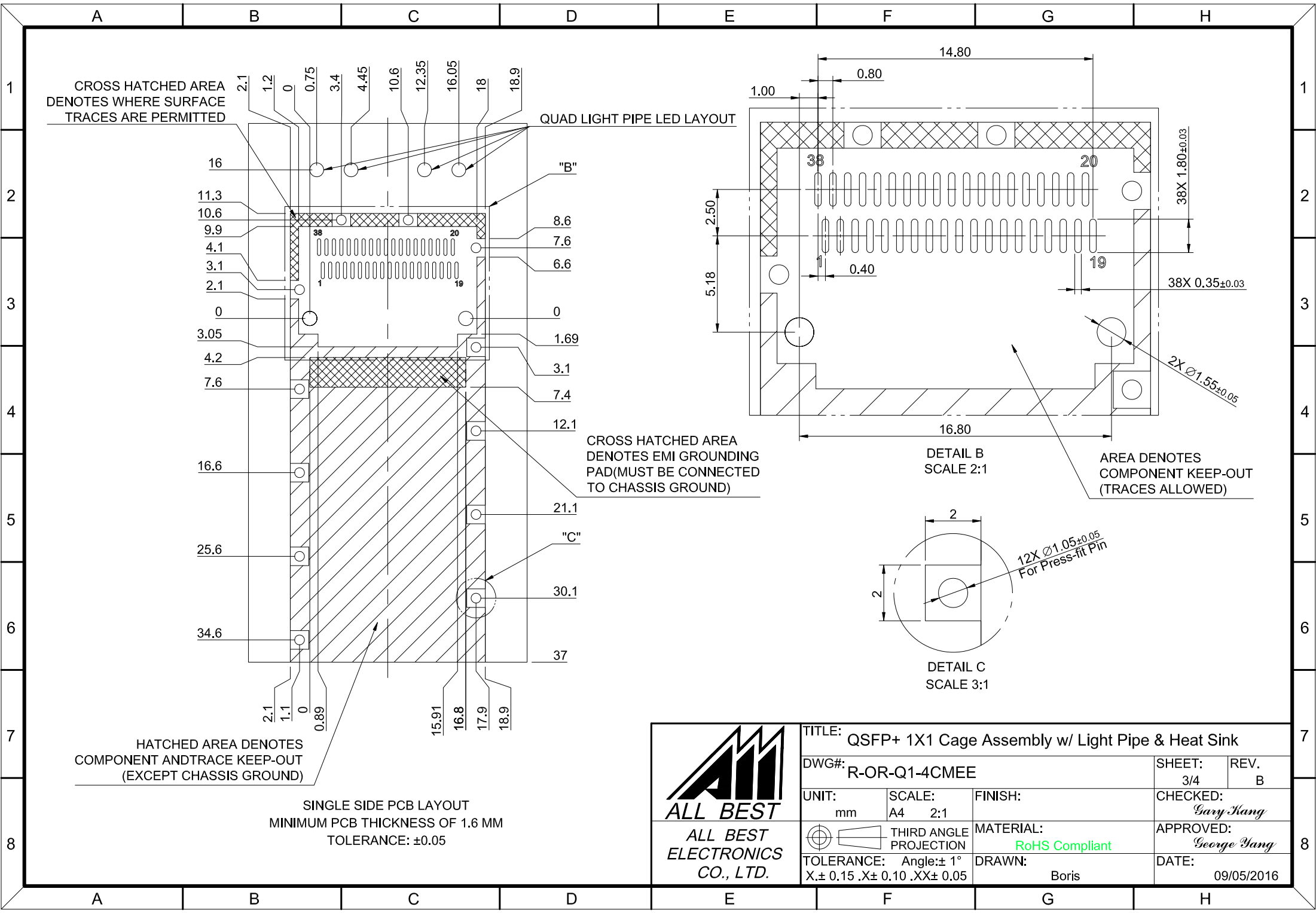


BELLY TO BELLY CONFIGURATION

C=THICKNESS OF PC BOARD
 SINGLE SIDED=1.6MM(MIN)
 DOUBLE SIDE=2.2MM(MIN)



	TITLE: QSFP+ 1X1 Cage Assembly w/ Light Pipe & Heat Sink			SHEET: 2/4		REV. B	
	DWG#: R-OR-Q1-4CMEE			CHECKED: Gary Kang		APPROVED: George Yang	
	UNIT: mm	SCALE: A4 1:1	FINISH:	MATERIAL: RoHS Compliant		DATE: 09/06/2016	
	TOLERANCE: X.± 0.15 .X± 0.10 .XX± 0.05		THIRD ANGLE PROJECTION	DRAWN: Boris			



CROSS HATCHED AREA DENOTES WHERE SURFACE TRACES ARE PERMITTED

QUAD LIGHT PIPE LED LAYOUT

CROSS HATCHED AREA DENOTES EMI GROUNDING PAD (MUST BE CONNECTED TO CHASSIS GROUND)


DETAIL B SCALE 2:1

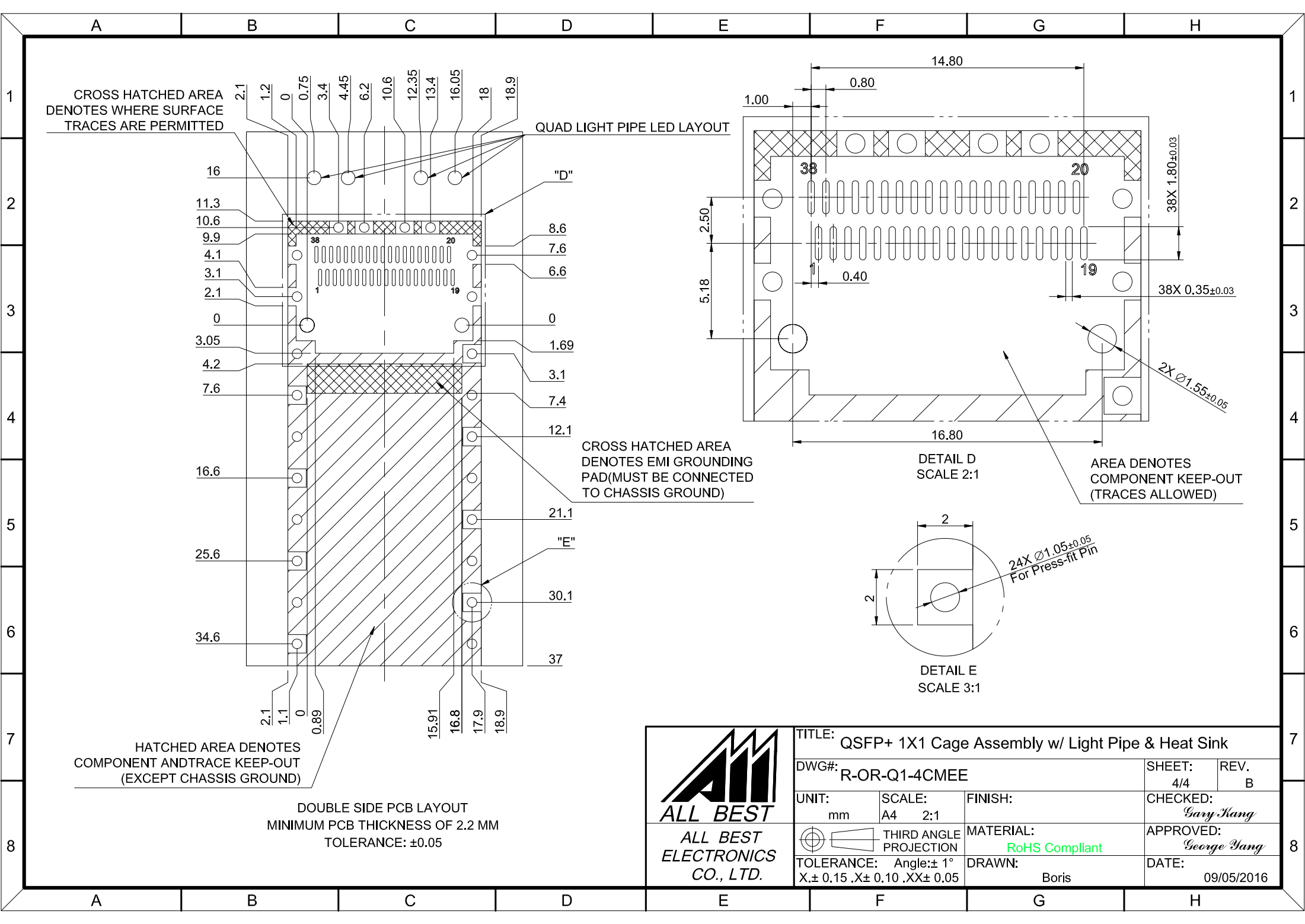
AREA DENOTES COMPONENT KEEP-OUT (TRACES ALLOWED)

DETAIL C SCALE 3:1

HATCHED AREA DENOTES COMPONENT AND TRACE KEEP-OUT (EXCEPT CHASSIS GROUND)

SINGLE SIDE PCB LAYOUT
MINIMUM PCB THICKNESS OF 1.6 MM
TOLERANCE: ±0.05

 ALL BEST ELECTRONICS CO., LTD.	TITLE: QSFP+ 1X1 Cage Assembly w/ Light Pipe & Heat Sink			SHEET: 3/4	REV. B
	DWG#: R-OR-Q1-4CMEE		CHECKED: Gary Yang		APPROVED: George Yang
	UNIT: mm	SCALE: A4 2:1	FINISH:	MATERIAL: RoHS Compliant	
	TOLERANCE: X±0.15 .X±0.10 .XX±0.05		THIRD ANGLE PROJECTION	DRAWN: Boris	DATE: 09/05/2016



CROSS HATCHED AREA DENOTES WHERE SURFACE TRACES ARE PERMITTED

QUAD LIGHT PIPE LED LAYOUT

CROSS HATCHED AREA DENOTES EMI GROUNDING PAD (MUST BE CONNECTED TO CHASSIS GROUND)

HATCHED AREA DENOTES COMPONENT AND TRACE KEEP-OUT (EXCEPT CHASSIS GROUND)

DOUBLE SIDE PCB LAYOUT
MINIMUM PCB THICKNESS OF 2.2 MM
TOLERANCE: ±0.05

DETAIL D
SCALE 2:1

AREA DENOTES COMPONENT KEEP-OUT (TRACES ALLOWED)

DETAIL E
SCALE 3:1

<p>ALL BEST ELECTRONICS CO., LTD.</p>	TITLE: QSFP+ 1X1 Cage Assembly w/ Light Pipe & Heat Sink			SHEET: 4/4		REV. B
	DWG#: R-OR-Q1-4CMEE			CHECKED: Gary Kang		
	UNIT: mm	SCALE: A4 2:1	FINISH:	APPROVED: George Yang		
	TOLERANCE: X ± 0.15, .X ± 0.10, .XX ± 0.05		THIRD ANGLE PROJECTION	MATERIAL: RoHS Compliant	DATE: 09/05/2016	
DRAWN: Boris						